THIS SHEET HAS BEEN REPLACED

DIRECT CHIP ATTACH FOR LOW ALPHA EMISSION INTERCONNECT SYSTEM

ABSTRACT

An interconnect system that has low alpha particle emission characteristics for use in an electronic device includes a semiconductor chip (12) that has an upper surface and spaced apart electrically resistive bumps (26) positioned on conductive regions (18) of the upper surface, the electrically resistive bumps (26) are made of a composite material of a polymer and metal particles, and a substrate (12) that has conductive regions (18) bonded to the electrically resistive bumps (26) in a bonding process wherein the electrically resistive bumps convert to electrically conductive bumps after the bonding process.

Fig. 2A

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